



B



D

E

F

Derating diagram acc. to IEC 60512-5 (Current carrying capacity)

With a configuration of two power contacts, GND and ENA, the current carrying capacity is even up to 23A @ 70°C / 80% derating per contact.

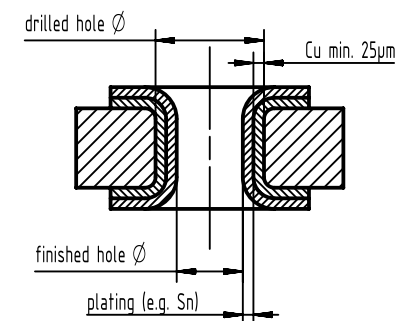


Scale
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STORCK

Rev. C

In addition to the hot-air-level (HAL), other PCB surfaces are getting more important. Due to their different properties - such as mechanical strength and coefficient of friction - we recommend the following configuration of PCB through holes.



Tin plated PCB (HAL) acc. to EN 60352-5	Drilled hole Ø	1,15±0,025 mm
	Sn	max. 15 µm
	plated hole Ø	0,94 - 1,09 mm
Chemical tin plated PCB	Drilled hole Ø	1,15±0,025 mm
	Sn	min. 0,8µm
	plated hole Ø	1,00 - 1,10 mm
Gold /Nickel plated PCB	Drilled hole Ø	1,15±0,025 mm
	Ni	3 - 7 µm
	Au	0,05 - 0,12 µm
	plated hole Ø	1,00 - 1,10 mm
Silver plated PCB	Drilled hole Ø	1,15±0,025 mm
	Ag	0,1 - 0,3 µm
	plated hole Ø	1,00 - 1,10 mm
Copper plated PCB (OSP)	Drilled hole Ø	1,15±0,025 mm
	plated hole Ø	1,00 - 1,10 mm

Assembly instructions

To press in correctly, use a flat upper tool, e.g. HARTING-tool 07790000156. The lower tool can be a customer manufactured loadnest.